













develop a promising sensor that can measure simultaneously tensile strain and temperature, which is an excellent advantage of overcoming the cross-sensitivity problem between tensile strain and temperature in practical sensing applications of smart engineering structures. In other words, tensile strain can be measured via intensity modulation of interference fringe with a high sensitivity of  $-0.023 \text{ dB}/\mu\epsilon$  and a measurement range of up to  $500 \mu\epsilon$ . And temperature can be measured via wavelength modulation of interference fringe with a very high sensitivity of  $51 \text{ pm}/^\circ\text{C}$ . Therefore, our MZI-based sensor can realize simultaneous measurement of tensile strain and temperature.

It can be found from Figs. 4(b) and 5(b) that the fluctuation of the dip wavelength is less than  $0.04 \text{ nm}$  while tensile strain is less than  $500 \mu\epsilon$  and the fluctuation of the dip intensity is less than  $0.028 \text{ dBm}$  during temperature rise. As a result, the strain-caused error of the dip wavelength and the temperature-caused error of the dip intensity are less than  $0.8 \text{ }^\circ\text{C}$  and less than  $1.2 \mu\epsilon$ , respectively, during simultaneous measurement of tensile strain and temperature, which can meet the sensing applications in smart engineering structures.

## 5. Conclusion

In conclusion, a novel fiber in-line MZI with a misalignment-spliced joint was demonstrated to develop a promising sensor that can realize simultaneous measurement of tensile strain and temperature. The strain and temperature sensitivities of the proposed sensor are  $-0.023 \text{ dB}/\mu\epsilon$  and  $51 \text{ pm}/^\circ\text{C}$ , respectively. Such a sensor overcomes the cross-sensitivity problem between tensile strain and temperature. Furthermore, our MZI-based sensor exhibits the merits of compact size (only about  $8 \text{ mm}$ ), high sensitivities, intensity-modulated for strain, good repeatability and mechanical reliability so that it is a good candidate of next-generation sensors in smart engineering structures.

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